

# SOT1339-1

plastic low profile fine-pitch ball grid array package; 217 balls

8 June 2016

Package information

## 1. Package summary

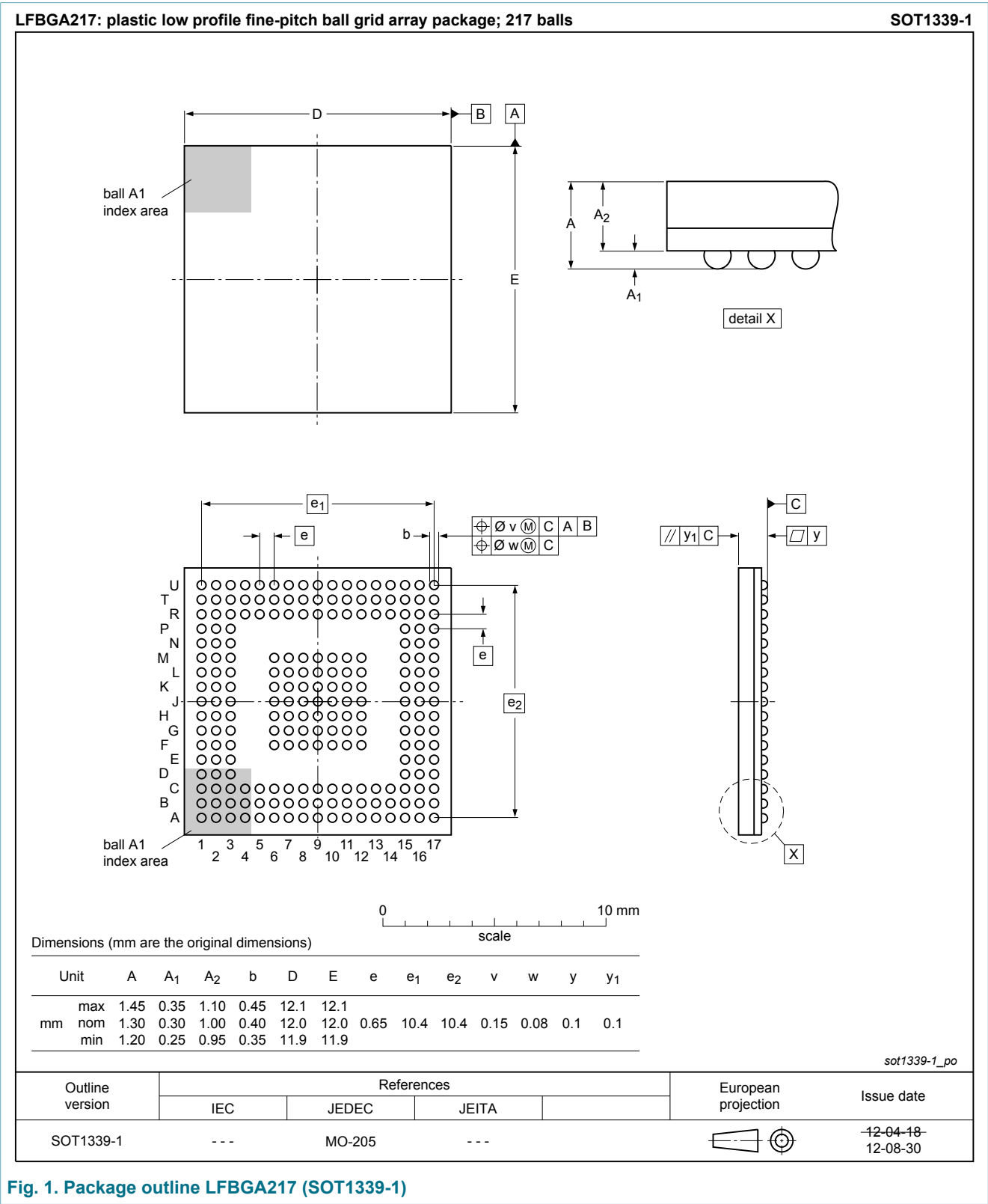
<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFBGA217
<b>Package type industry code</b>	LFBGA217
<b>Package style descriptive code</b>	LFBGA (low profile fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-205
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	20-9-2012

Table 1. Package summary

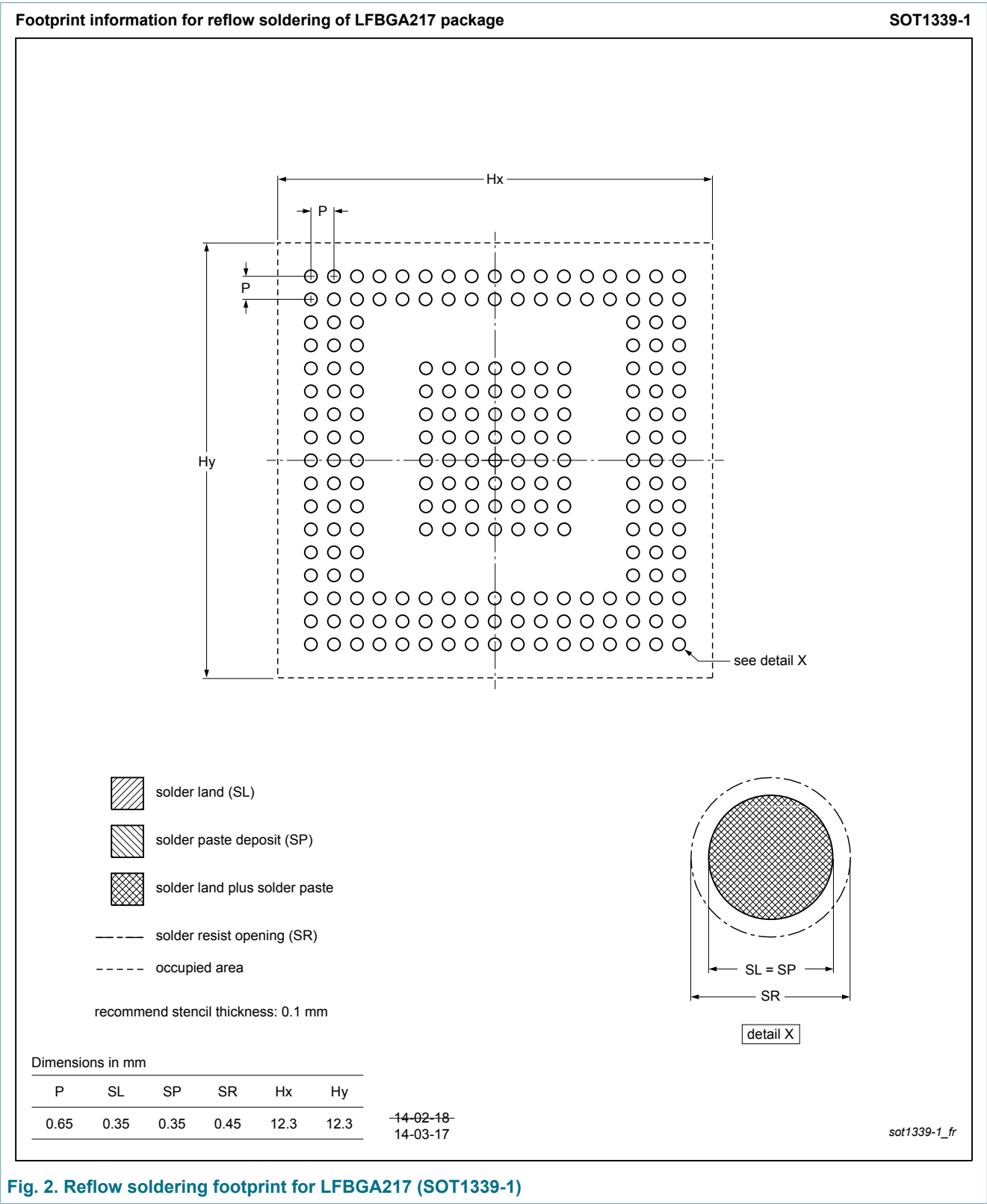
Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		11.9	-	12	12.1	mm
E	package width		11.9	-	12	12.1	mm
A	seated height		1.2	-	1.3	1.45	mm
A <sub>2</sub>	package height		0.95	-	1	1.1	mm
e	nominal pitch		-	-	0.65	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	217	-	



2. Package outline



3. Soldering



## 4. Legal information

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5. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Soldering..... 3

4. Legal information..... 4

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